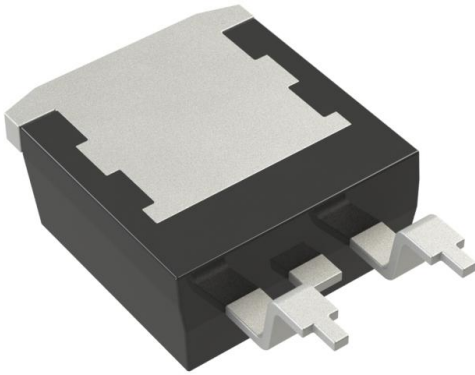


# IXTA26P10T Datasheet

[www.digi-electronics.com](http://www.digi-electronics.com)



<https://www.DiGi-Electronics.com>

DiGi Electronics Part Number	IXTA26P10T-DG
Manufacturer	<a href="#">IXYS</a>
Manufacturer Product Number	IXTA26P10T
Description	MOSFET P-CH 100V 26A TO263
Detailed Description	P-Channel 100 V 26A (Tc) 150W (Tc) Surface Mount TO-263AA



Tel: +00 852-30501935

RFQ Email: [Info@DiGi-Electronics.com](mailto:Info@DiGi-Electronics.com)

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## Purchase and inquiry

Manufacturer Product Number:

IXTA26P10T

Series:

TrenchP™

FET Type:

P-Channel

Drain to Source Voltage (Vdss):

100 V

Drive Voltage (Max Rds On, Min Rds On):

10V

Vgs(th) (Max) @ Id:

4.5V @ 250µA

Vgs (Max):

±15V

FET Feature:

-

Operating Temperature:

-55°C ~ 150°C (Tj)

Supplier Device Package:

TO-263AA

Base Product Number:

IXTA26

Manufacturer:

IXYS

Product Status:

Active

Technology:

MOSFET (Metal Oxide)

Current - Continuous Drain (Id) @ 25°C:

26A (Tc)

Rds On (Max) @ Id, Vgs:

90mOhm @ 13A, 10V

Gate Charge (Qg) (Max) @ Vgs:

52 nC @ 10 V

Input Capacitance (Ciss) (Max) @ Vds:

3820 pF @ 25 V

Power Dissipation (Max):

150W (Tc)

Mounting Type:

Surface Mount

Package / Case:

TO-263-3, D2PAK (2 Leads + Tab), TO-263AB

## Environmental & Export classification

RoHS Status:

ROHS3 Compliant

REACH Status:

REACH Unaffected

HTSUS:

8541.29.0095

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99

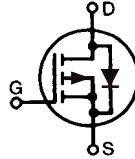


# TrenchP™ Power MOSFET

## IXTY26P10T IXTA26P10T IXTP26P10T

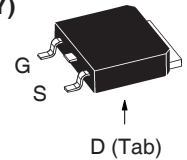
$$\begin{aligned} V_{DSS} &= -100V \\ I_{D25} &= -26A \\ R_{DS(on)} &\leq 90m\Omega \end{aligned}$$

P-Channel Enhancement Mode  
Avalanche Rated

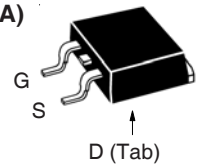


Symbol	Test Conditions	Maximum Ratings	
$V_{DSS}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$	- 100	V
$V_{DGR}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$ , $R_{GS} = 1M\Omega$	- 100	V
$V_{GSS}$	Continuous	$\pm 15$	V
$V_{GSM}$	Transient	$\pm 25$	V
$I_{D25}$	$T_C = 25^\circ\text{C}$	- 26	A
$I_{DM}$	$T_C = 25^\circ\text{C}$ , Pulse Width Limited by $T_{JM}$	- 80	A
$I_A$	$T_C = 25^\circ\text{C}$	- 26	A
$E_{AS}$	$T_C = 25^\circ\text{C}$	300	mJ
$P_D$	$T_C = 25^\circ\text{C}$	150	W
$T_J$		-55 ... +150	$^\circ\text{C}$
$T_{JM}$		150	$^\circ\text{C}$
$T_{stg}$		-55 ... +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering	300	$^\circ\text{C}$
$T_{SOLD}$	1.6 mm (0.062in.) from Case for 10s	260	$^\circ\text{C}$
$M_d$	Mounting Torque (TO-220)	1.13 / 10	Nm/lb.in
<b>Weight</b>	TO-252	0.35	g
	TO-263	2.50	g
	TO-220	3.00	g

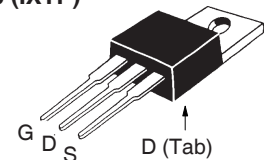
TO-252 (IXTY)



TO-263 (IXTA)



TO-220 (IXTP)



G = Gate      D = Drain  
S = Source    Tab = Drain

### Features

- International Standard Packages
- Avalanche Rated
- Extended FBSOA
- Fast Intrinsic Diode
- Low  $R_{DS(ON)}$  and  $Q_G$

### Advantages

- Easy to Mount
- Space Savings
- High Power Density

### Applications

- High-Side Switching
- Push Pull Amplifiers
- DC Choppers
- Automatic Test Equipment
- Current Regulators
- Battery Charger Applications

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$BV_{DSS}$	$V_{GS} = 0V$ , $I_D = -250\mu\text{A}$	-100		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = -250\mu\text{A}$	- 2.5		- 4.5 V
$I_{GSS}$	$V_{GS} = \pm 15V$ , $V_{DS} = 0V$			$\pm 50$ nA
$I_{DSS}$	$V_{DS} = V_{DSS}$ , $V_{GS} = 0V$ $T_J = 125^\circ\text{C}$			-10 $\mu\text{A}$ - 250 $\mu\text{A}$
$R_{DS(on)}$	$V_{GS} = -10V$ , $I_D = 0.5 \cdot I_{D25}$ , Note 1			90 m $\Omega$



IXTY26P10T IXTA26P10T  
IXTP26P10T

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$g_{fs}$	$V_{DS} = -10\text{V}$ , $I_D = 0.5 \cdot I_{D25}$ , Note 1	10	17	S
$C_{iss}$	$V_{GS} = 0\text{V}$ , $V_{DS} = -25\text{V}$ , $f = 1\text{MHz}$		3820	pF
$C_{oss}$			280	pF
$C_{rss}$			93	pF
$t_{d(on)}$	<b>Resistive Switching Times</b> $V_{GS} = -10\text{V}$ , $V_{DS} = 0.5 \cdot V_{DSS}$ , $I_D = 0.5 \cdot I_{D25}$ $R_G = 3\Omega$ (External)		20	ns
$t_r$			15	ns
$t_{d(off)}$			37	ns
$t_f$			11	ns
$Q_{g(on)}$	$V_{GS} = -10\text{V}$ , $V_{DS} = 0.5 \cdot V_{DSS}$ , $I_D = 0.5 \cdot I_{D25}$		52	nC
$Q_{gs}$			18	nC
$Q_{gd}$			16	nC
$R_{thJC}$	TO-220			0.83 $^\circ\text{C/W}$
$R_{thCS}$			0.50	$^\circ\text{C/W}$

#### Source-Drain Diode

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$I_S$	$V_{GS} = 0\text{V}$			-26 A
$I_{SM}$	Repetitive, Pulse Width Limited by $T_{JM}$			-104 A
$V_{SD}$	$I_F = I_S$ , $V_{GS} = 0\text{V}$ , Note 1			-1.5 V
$t_{rr}$	$I_F = 0.5 \cdot I_{D25}$ , $-di/dt = -100\text{A}/\mu\text{s}$ $V_R = -50\text{V}$ , $V_{GS} = 0\text{V}$		70	ns
$Q_{RM}$			210	nC
$I_{RM}$			-6	A

Note 1: Pulse test,  $t \leq 300\mu\text{s}$ , duty cycle,  $d \leq 2\%$ .

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:	4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065B1	6,683,344	6,727,585	7,005,734B2	7,157,338B2
	4,860,072	5,017,508	5,063,307	5,381,025	6,259,123B1	6,534,343	6,710,405B2	6,759,692	7,063,975B2	
	4,881,106	5,034,796	5,187,117	5,486,715	6,306,728B1	6,583,505	6,710,463	6,771,478B2	7,071,537	

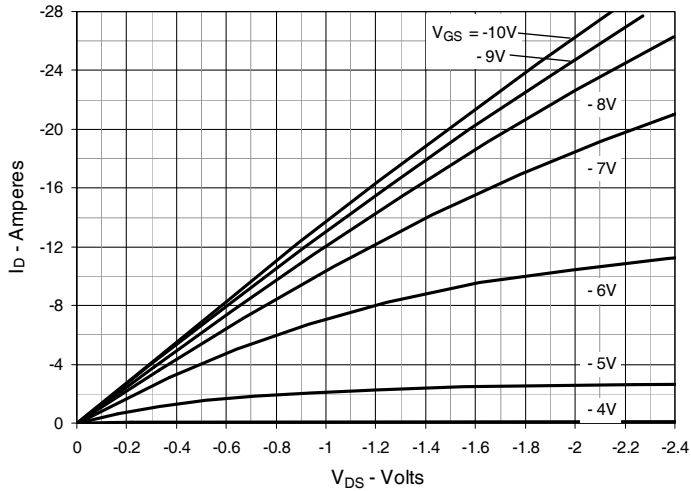
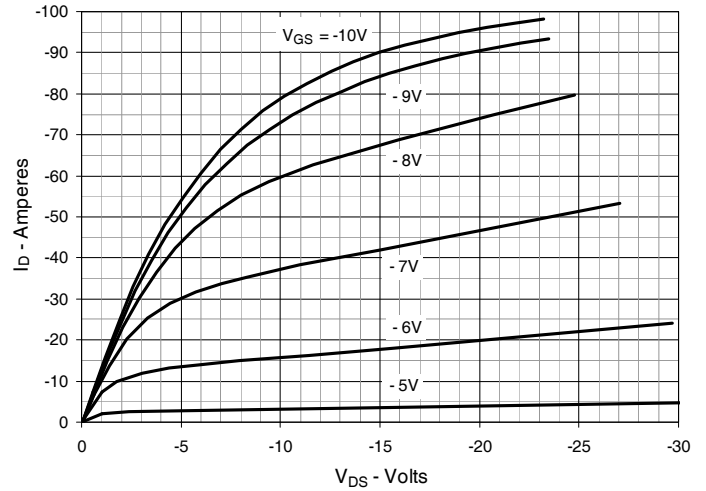
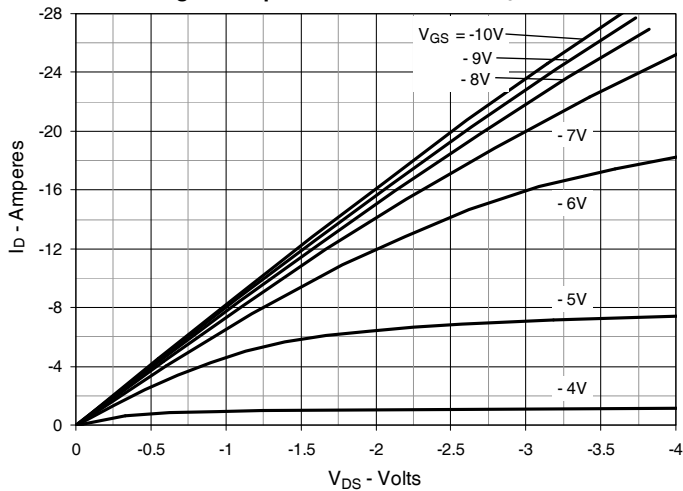
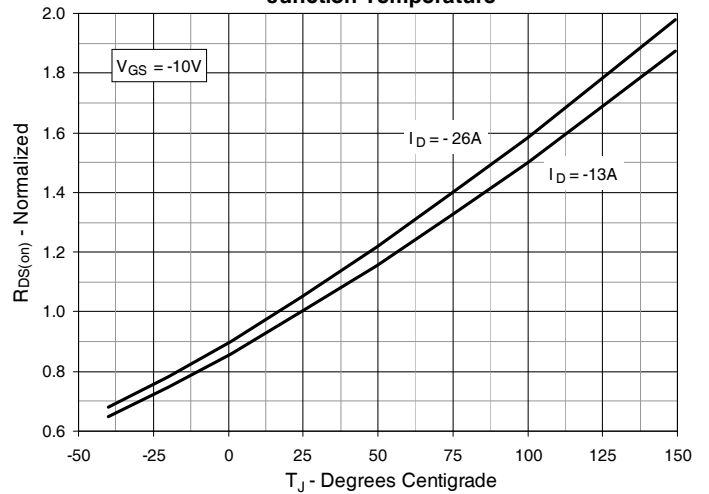
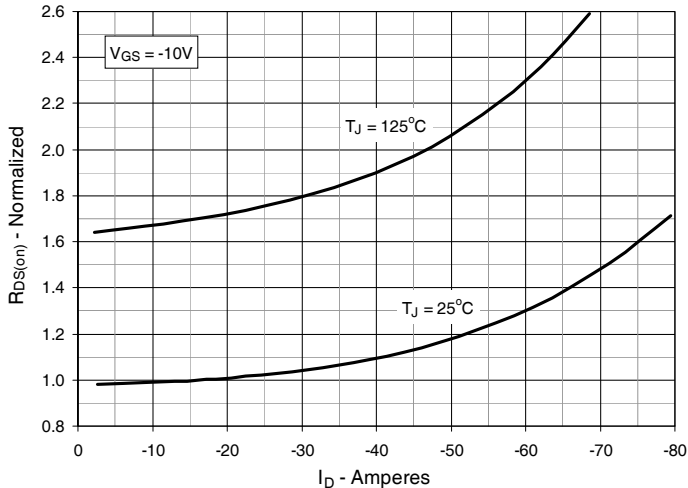
Fig. 1. Output Characteristics @  $T_J = 25^\circ\text{C}$ Fig. 2. Extended Output Characteristics @  $T_J = 25^\circ\text{C}$ Fig. 3. Output Characteristics @  $T_J = 125^\circ\text{C}$ Fig. 4.  $R_{DS(on)}$  Normalized to  $I_D = -13\text{A}$  Value vs. Junction TemperatureFig. 5.  $R_{DS(on)}$  Normalized to  $I_D = -13\text{A}$  Value vs. Drain Current

Fig. 6. Maximum Drain Current vs. Case Temperature

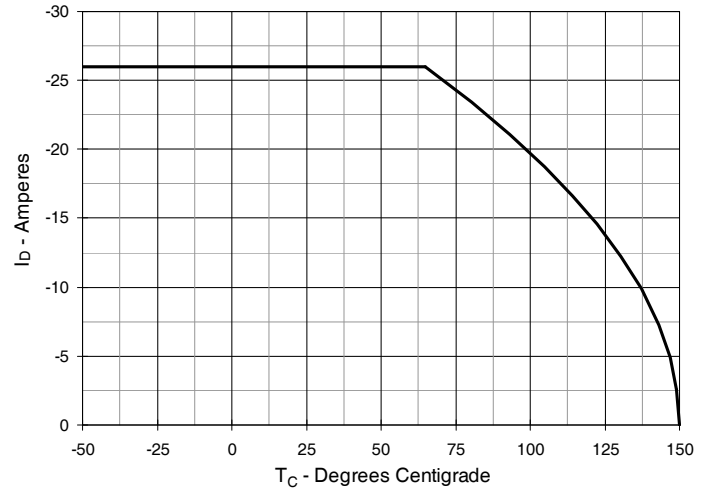


Fig. 7. Input Admittance

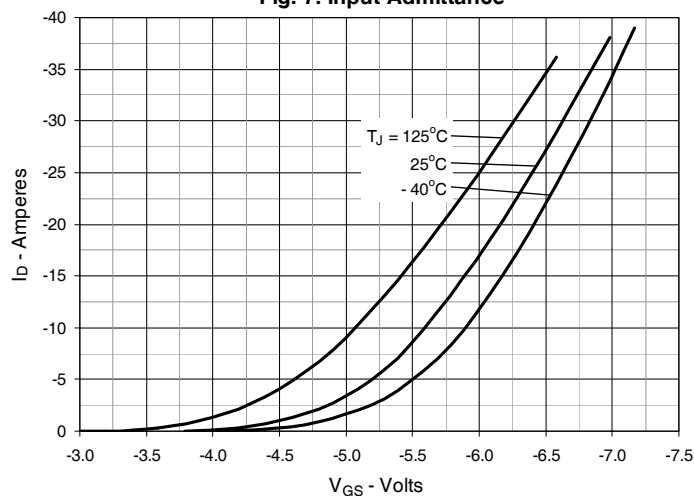


Fig. 8. Transconductance

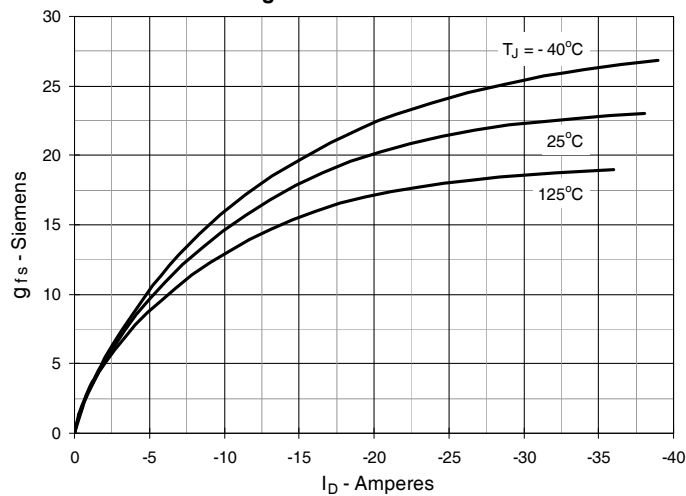


Fig. 9. Forward Voltage Drop of Intrinsic Diode

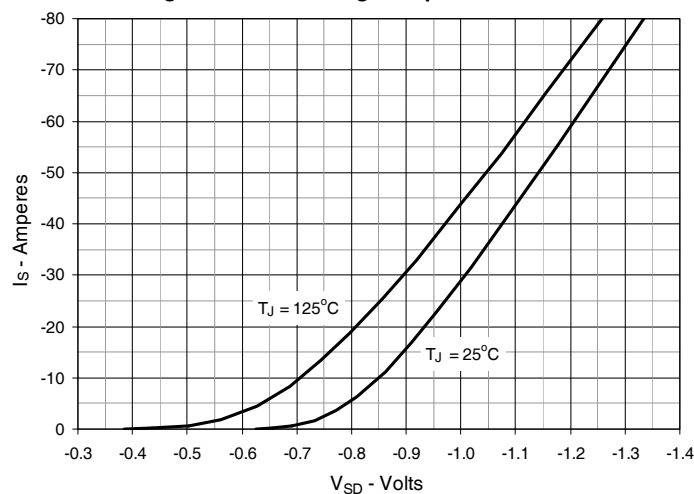


Fig. 10. Gate Charge

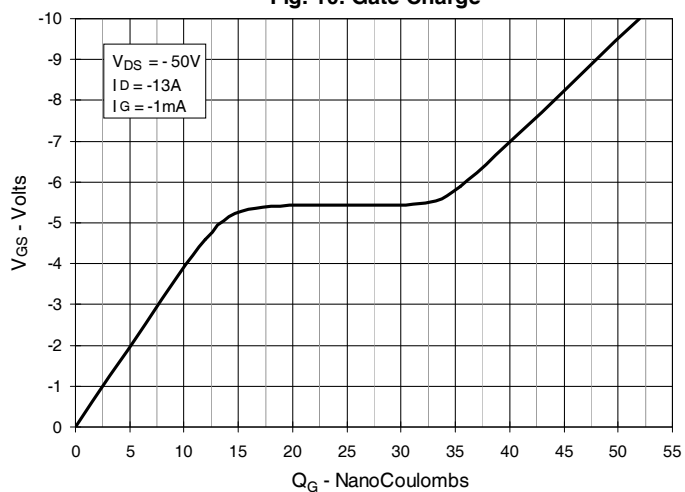


Fig. 11. Capacitance

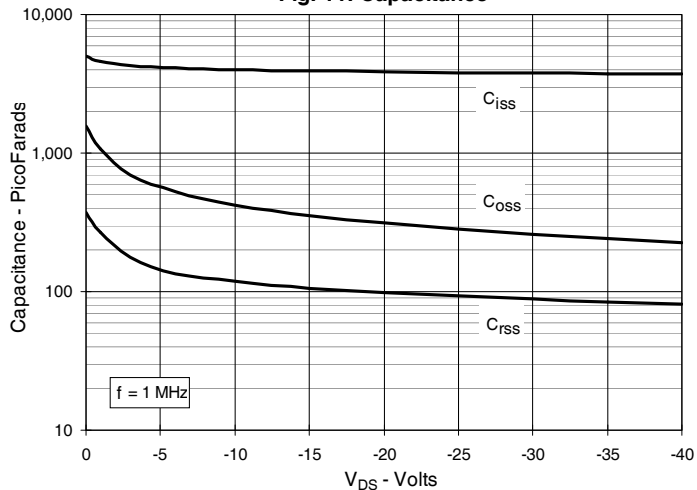


Fig. 12. Forward-Bias Safe Operating Area

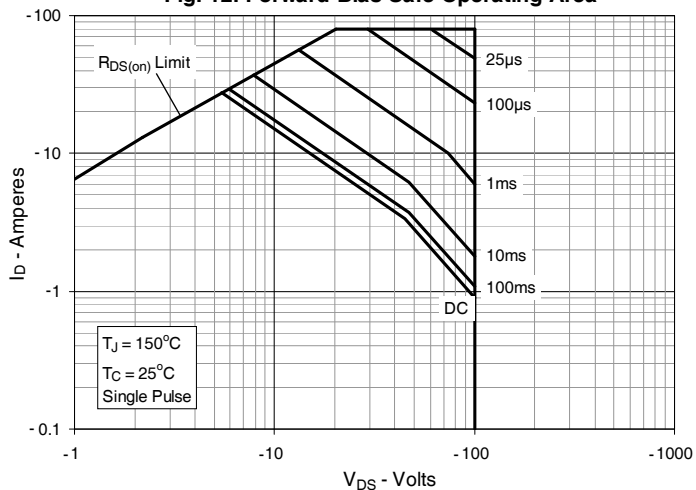


Fig. 13. Resistive Turn-on Rise Time vs. Junction Temperature

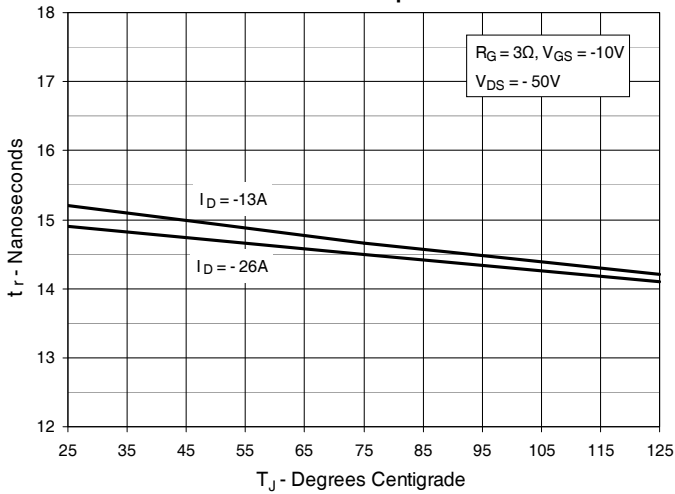


Fig. 14. Resistive Turn-on Rise Time vs. Drain Current

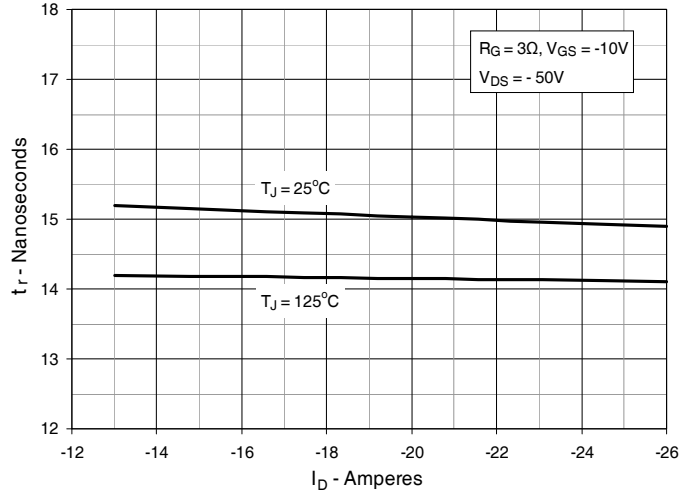


Fig. 15. Resistive Turn-on Switching Times vs. Gate Resistance

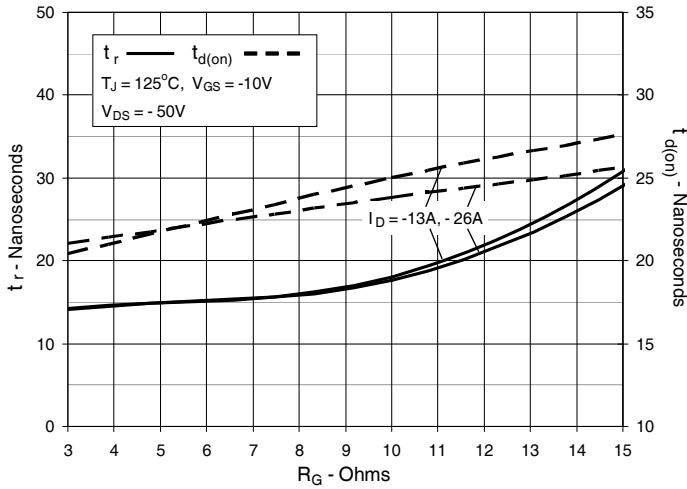


Fig. 16. Resistive Turn-off Switching Times vs. Junction Temperature

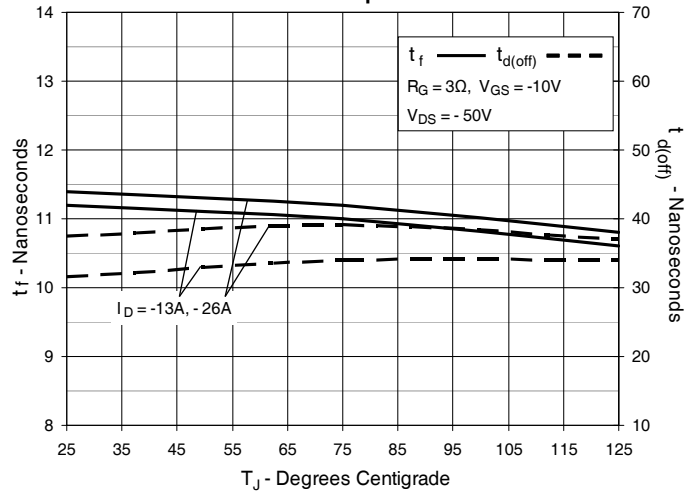


Fig. 17. Resistive Turn-off Switching Times vs. Drain Current

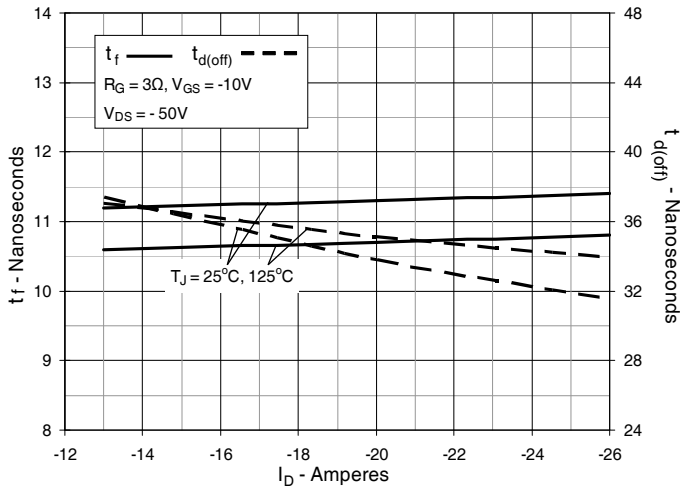


Fig. 18. Resistive Turn-off Switching Times vs. Gate Resistance

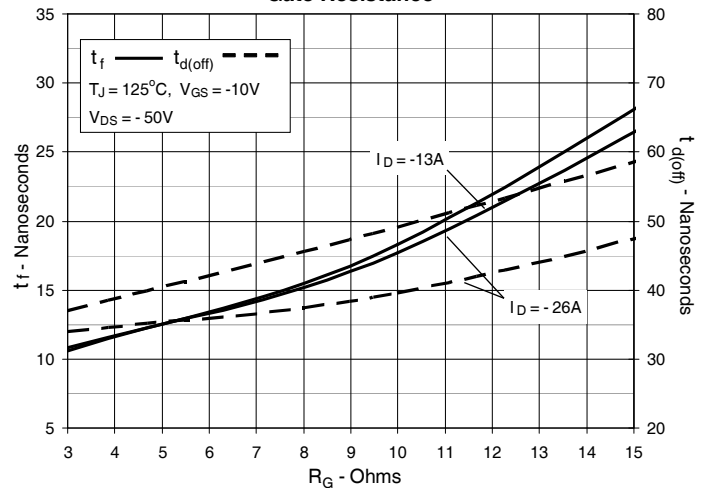
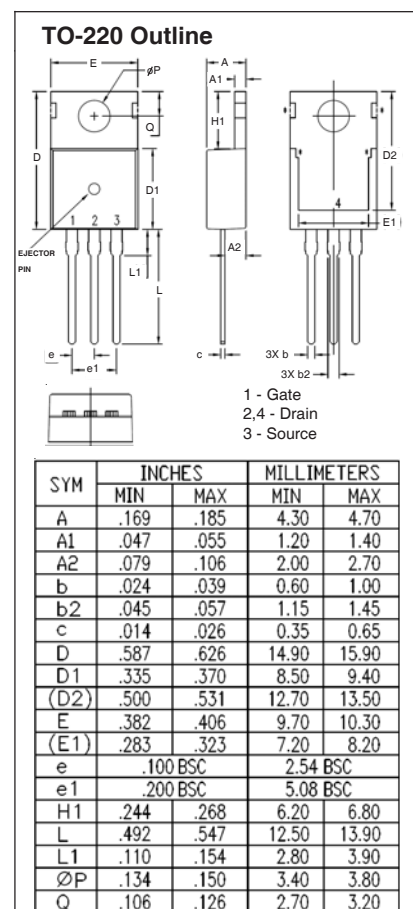
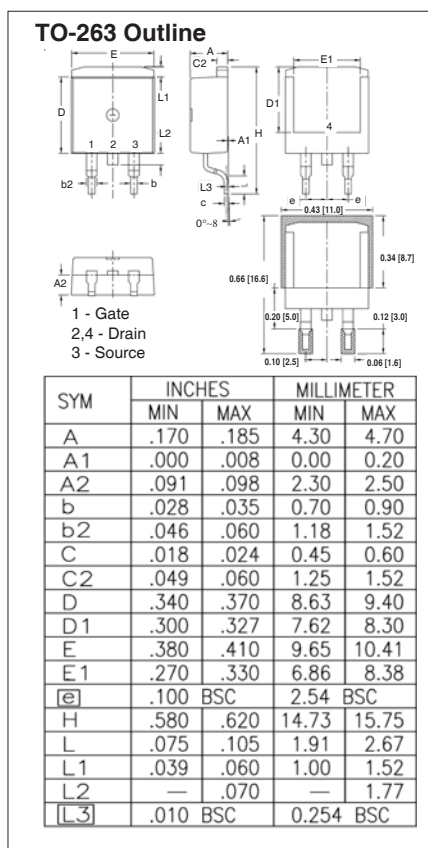
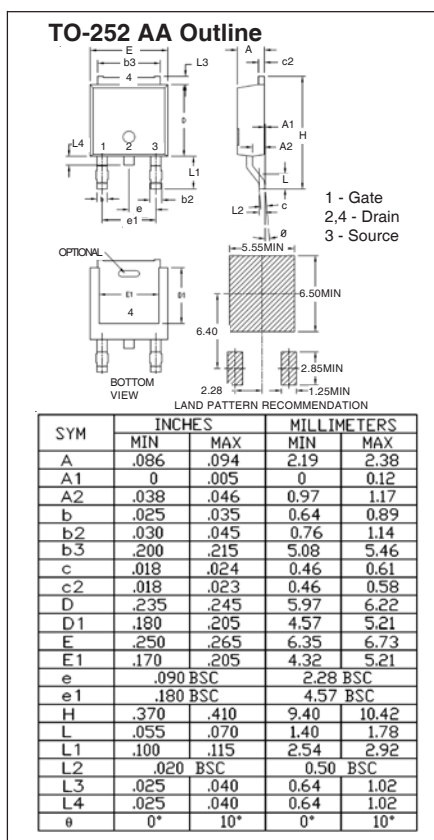
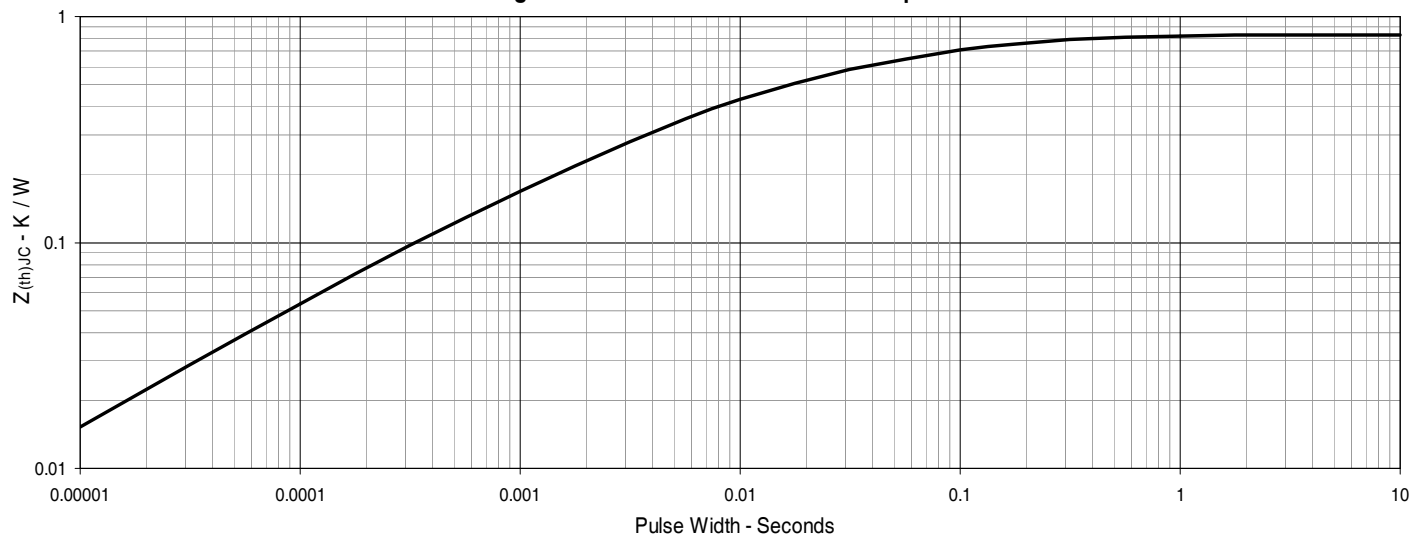


Fig. 19. Maximum Transient Thermal Impedance



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